

CONFIGURABLE MULTIPLE-FUNCTION GATE
Description

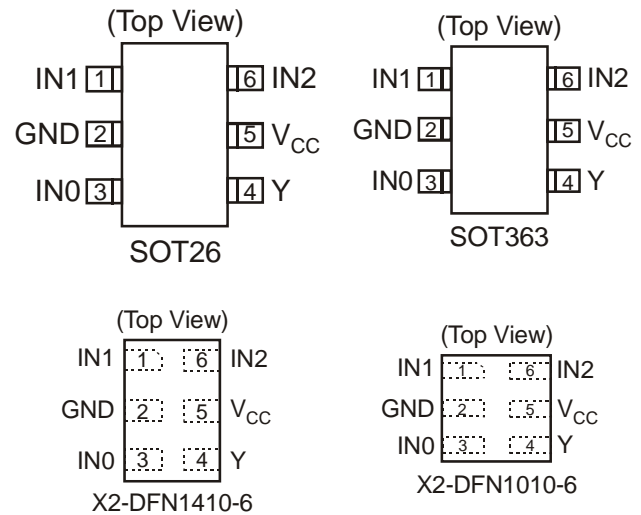
The DIODES™ 74LVC1G97 is a single three-input positive configurable multiple function gate with a standard push-pull output. The output state is determined by eight patterns of three-bit input. The user can choose the logic functions MUX, AND, OR, NAND, NOR, inverter or non-inverting buffer. All inputs can be connected to ground or Vcc as required. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using IOFF. The IOFF circuitry disables the output preventing damaging current backflow when the device is powered down. The user is reminded that the device can simulate several types of logic gates but may respond differently due to the Schmitt action at the inputs.

Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- ± 24mA Output Drive at 3.3V
- CMOS Low Power Consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs Accept up to 5.5V
- ESD Protection Exceeds JESD 22
 - 200-V Machine Model (A115-A)
 - 2000-V Human Body Model (A114-A)
- Latch-Up Exceeds 100mA per JESD 78, Class II
- Range of Package Options
- SOT26, SOT363, X2-DFN1410-6, and X2-DFN1010-6: Available in "Green" Molding Compound (no Br, Sb)
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

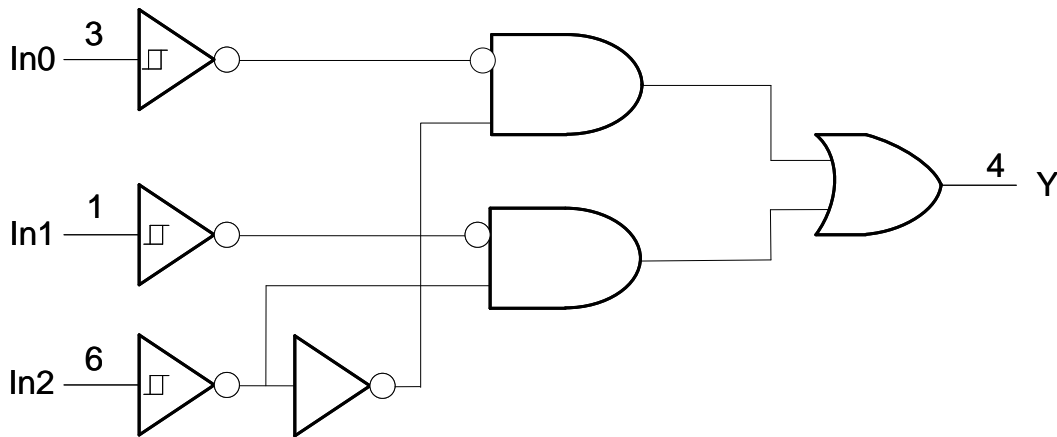
Pin Assignments

Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products such as:
 - PCs, networking, notebooks, netbooks, PDAs
 - Computer peripherals, hard drives, CD/DVD ROM
 - TV, DVD, DVR, set top box
 - Cell Phones, Personal Navigation / GPS
 - MP3 players, Cameras, Video Recorders

Pin Descriptions

| Pin Name | Description |
|-----------------|----------------|
| IN1 | Data Input |
| GND | Ground |
| IN0 | Data Input |
| Y | Data Output |
| V _{CC} | Supply Voltage |
| IN2 | Data Input |

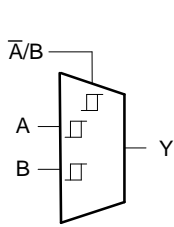
Logic Diagram



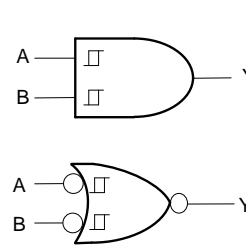
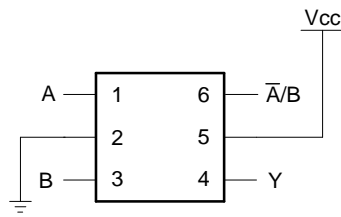
Function Table

| Inputs | | | Output |
|--------|-----|-----|--------|
| IN2 | IN1 | IN0 | Y |
| L | L | L | L |
| L | L | H | L |
| L | H | L | H |
| L | H | H | H |
| H | L | L | L |
| H | L | H | H |
| H | H | L | L |
| H | H | H | H |

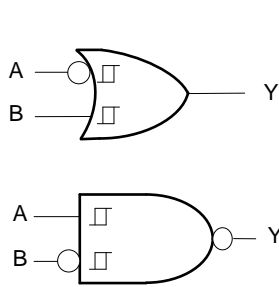
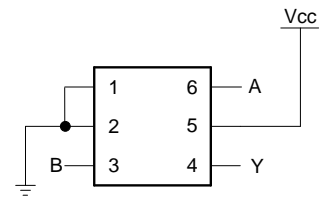
Logic Configurations



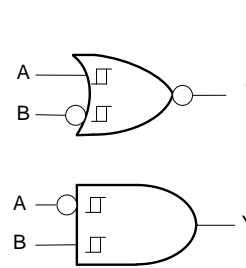
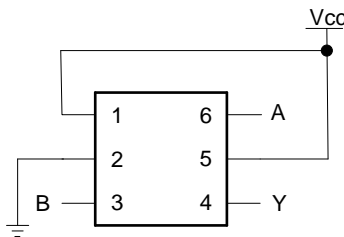
Configuration 1
2 to 1 Data Selector



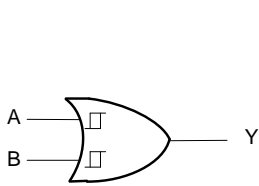
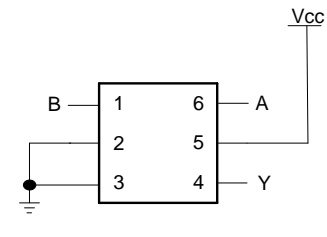
Configuration 2
2-Input AND Gate
2-Input NOR Gate with Both Inputs Inverted



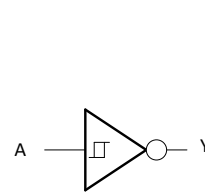
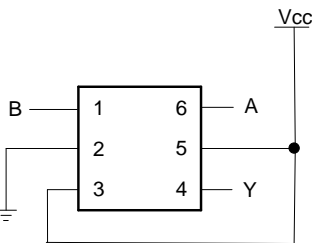
Configuration 3
2-Input NAND Gate with B Input Inverted
2-Input OR Gate with A Input Inverted



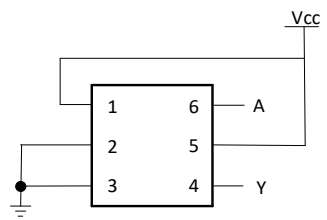
Configuration 4
2-Input NOR Gate with One Input Inverted
2-Input AND Gate with One Input Inverted



Configuration 5
2-Input OR Gate



Configuration 6
Inverter



| Function Selection Table | |
|---------------------------------------|---------------|
| Logic Function | Configuration |
| 2-to-1 Data Selector | 1 |
| 2-input AND gate | 2 |
| 2-input AND with inverted input | 3, 4 |
| 2-input NOR with inverted input | 3, 4 |
| 2-input OR | 5 |
| 2-input NOR with both inputs inverted | 2 |
| 1-input Inverter | 6 |

Absolute Maximum Ratings (Note 4)

| Symbol | Description | Rating | Unit |
|------------------|---|------------------------------|------|
| ESD HBM | Human Body Model ESD Protection | 2 | kV |
| ESD MM | Machine Model ESD Protection | 200 | V |
| V _{CC} | Supply Voltage Range | -0.5 to 6.5 | V |
| V _I | Input Voltage Range | -0.5 to 6.5 | V |
| V _O | Voltage applied to output in high impedance or I _{OFF} state | -0.5 to 6.5 | V |
| V _O | Voltage applied to output in high or low state | -0.3 to V _{CC} +0.5 | V |
| I _{IK} | Input Clamp Current V _I < 0 | -50 | mA |
| I _{OK} | Output Clamp Current | -50 | mA |
| I _O | Continuous output current | ±50 | mA |
| | Continuous current through V _{DD} or GND | ±100 | mA |
| T _J | Operating Junction Temperature | -40 to +150 | °C |
| T _{STG} | Storage Temperature | -65 to +150 | °C |

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 5)

| Symbol | Parameter | Min | Max | Unit | |
|-----------------|--------------------------------|-------------------------|-----------------|------|----|
| V _{CC} | Operating Voltage | Operating | 1.65 | 5.5 | V |
| | | Data retention only | 1.5 | — | V |
| V _I | Input Voltage | 0 | 5.5 | V | |
| V _O | Output Voltage | 0 | V _{CC} | V | |
| I _{OH} | High-Level Output Current | V _{CC} = 1.65V | — | -4 | mA |
| | | V _{CC} = 2.3V | — | -8 | |
| | | V _{CC} = 3V | — | -16 | |
| | | V _{CC} = 4.5V | — | -24 | |
| I _{OL} | Low-Level Output Current | V _{CC} = 1.65V | — | 4 | mA |
| | | V _{CC} = 2.3V | — | 8 | |
| | | V _{CC} = 3V | — | 16 | |
| | | V _{CC} = 4.5V | — | 24 | |
| T _A | Operating Free-Air Temperature | — | -40 | +125 | °C |

Note: 5. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@T_A = -40°C to +85°C. All typical values are at V_{CC} = 3.3V, T_A = +25°C)

| Symbol | Parameter | Test Conditions | V _{CC} | Min | Typ | Max | Unit |
|------------------|---|--|-----------------|-----------------------|-----|------|------|
| V _{T+} | Positive-going input threshold voltage | — | 1.65V | 0.70 | — | 1.20 | — |
| | | — | 2.3V | 1.11 | — | 1.60 | — |
| | | — | 3V | 1.50 | — | 2.00 | — |
| | | — | 4.5V | 2.16 | — | 2.74 | — |
| | | — | 5.5V | 2.61 | — | 3.33 | — |
| V _{T-} | Negative-going input threshold voltage | — | 1.65V | 0.30 | — | 0.72 | — |
| | | — | 2.3V | 0.58 | — | 1.00 | — |
| | | — | 3V | 0.80 | — | 1.30 | — |
| | | — | 4.5V | 1.21 | — | 1.95 | — |
| | | — | 5.5V | 1.45 | — | 2.35 | — |
| ΔV _T | Hysteresis (V _{T+} - V _{T-}) | — | 1.65V | 0.30 | — | 0.62 | — |
| | | — | 2.3V | 0.40 | — | 0.80 | — |
| | | — | 3V | 0.35 | — | 1.00 | — |
| | | — | 4.5V | 0.55 | — | 1.10 | — |
| | | — | 5.5V | 0.60 | — | 1.20 | — |
| V _{OH} | High Level Output Voltage | I _{OH} = -100μA | 1.65V to 5.5V | V _{CC} - 0.1 | — | — | V |
| | | I _{OH} = -4mA | 1.65V | 1.2 | — | — | |
| | | I _{OH} = -8mA | 2.3V | 1.9 | — | — | |
| | | I _{OH} = -16mA | 3V | 2.4 | — | — | |
| | | I _{OH} = -24mA | | 2.3 | — | — | |
| | | I _{OH} = -32mA | 4.5V | 3.8 | — | — | |
| V _{OL} | High-level Input Voltage | I _{OL} = 100μA | 1.65V to 5.5V | — | — | 0.1 | V |
| | | I _{OL} = 4mA | 1.65V | — | — | 0.45 | |
| | | I _{OL} = 8mA | 2.3V | — | — | 0.3 | |
| | | I _{OL} = 16mA | 3V | — | — | 0.4 | |
| | | I _{OL} = 24mA | | — | — | 0.55 | |
| | | I _{OL} = 32mA | 4.5V | — | — | 0.55 | |
| I _I | Input Current | V _I = 5.5V or GND | 0 to 5.5V | — | — | ± 1 | μA |
| I _{OFF} | Power Down Leakage Current | V _I or V _O = 5.5V | 0 | — | — | ± 2 | μA |
| I _{CC} | Supply Current | V _I = 5.5V of GND I _O =0 | 1.65V to 5.5V | — | — | 4 | μA |
| ΔI _{CC} | Additional Supply Current | One input at V _{CC} -0.6V Other inputs at V _{CC} or GND | 3V to 5.5V | — | — | 500 | μA |

Electrical Characteristics (Continued) (@T_A = -40°C to +85°C. All typical values are at V_{CC} = 3.3V, T_A = +25°C)

| Symbol | Parameter | Test Conditions | V _{CC} | Min | Typ | Max | Unit |
|------------------|---|--|-----------------|----------------------|-----|------|------|
| V _{T+} | Positive-going input threshold voltage | — | 1.65V | 0.70 | — | 1.20 | — |
| | | — | 2.3V | 1.11 | — | 1.60 | — |
| | | — | 3V | 1.50 | — | 2.00 | — |
| | | — | 4.5V | 2.16 | — | 2.74 | — |
| | | — | 5.5V | 2.61 | — | 3.33 | — |
| V _{T-} | Negative-going input threshold voltage | — | 1.65V | 0.30 | — | 0.75 | — |
| | | — | 2.3V | 0.58 | — | 1.03 | — |
| | | — | 3V | 0.80 | — | 1.33 | — |
| | | — | 4.5V | 1.21 | — | 1.95 | — |
| | | — | 5.5V | 1.45 | — | 2.35 | — |
| ΔV _T | Hysteresis (V _{T+} - V _{T-}) | — | 1.65V | 0.30 | — | 0.62 | — |
| | | — | 2.3V | 0.37 | — | 0.80 | — |
| | | — | 3V | 0.32 | — | 1.00 | — |
| | | — | 4.5V | 0.50 | — | 1.20 | — |
| | | — | 5.5V | 0.55 | — | 1.40 | — |
| V _{OH} | High Level Output Voltage | I _{OH} = -100μA | 1.65V to 5.5V | V _{CC} -0.1 | — | — | V |
| | | I _{OH} = -4mA | 1.65V | 0.95 | — | — | |
| | | I _{OH} = -8mA | 2.3V | 1.7 | — | — | |
| | | I _{OH} = -16mA | 3V | 1.9 | — | — | |
| | | I _{OH} = -24mA | | 2.0 | — | — | |
| | | I _{OH} = -32mA | 4.5V | 3.4 | — | — | |
| V _{OL} | High-level Input Voltage | I _{OL} = 100μA | 1.65V to 5.5V | — | — | 0.1 | V |
| | | I _{OL} = 4mA | 1.65V | — | — | 0.7 | |
| | | I _{OL} = 8mA | 2.3V | — | — | 0.45 | |
| | | I _{OL} = 16mA | 3V | — | — | 0.6 | |
| | | I _{OL} = 24mA | | — | — | 0.8 | |
| | | I _{OL} = 32mA | 4.5V | — | — | 0.8 | |
| I _I | Input Current | V _I = 5.5V or GND | 0 to 5.5V | — | — | ± 1 | μA |
| I _{OFF} | Power Down Leakage Current | V _I or V _O = 5.5V | 0 | — | — | ± 2 | μA |
| I _{CC} | Supply Current | V _I = 5.5V of GND I _O =0 | 1.65V to 5.5V | — | — | 4 | μA |
| ΔI _{CC} | Additional Supply Current | One input at V _{CC} -0.6V Other inputs at V _{CC} or GND | 3V to 5.5V | — | — | 500 | μA |

Package Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$)

| Symbol | Parameter | Test Conditions | V_{CC} | Min | Typ | Max | Unit |
|---------------|--|--------------------------------|----------|-----|-----|-----|--------------|
| C_i | Input Capacitance | $V_i = V_{CC} - \text{or GND}$ | 3.3 | — | 3.5 | — | pF |
| θ_{JA} | Thermal Resistance Junction-to-Ambient | SOT26 | (Note 6) | — | 204 | — | $^\circ C/W$ |
| | | SOT363 | | — | 371 | — | |
| | | X2-DFN1410-6 | | — | 430 | — | |
| | | X2-DFN1010-6 | | — | 510 | — | |
| θ_{JC} | Thermal Resistance Junction-to-Case | SOT26 | (Note 6) | — | 52 | — | $^\circ C/W$ |
| | | SOT363 | | — | 143 | — | |
| | | X2-DFN1410-6 | | — | 190 | — | |
| | | X2-DFN1010-6 | | — | 250 | — | |

Note: 6. Test condition for SOT26, SOT363, X2-DFN1410-6 and X2-DFN1010-6 : Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

$T_A = -40^\circ C$ to $+85^\circ C$, $C_L = 30$ or $50pF$ as noted (See Figure 1)

| Parameter | From (Input) | TO (OUTPUT) | $V_{CC} = 1.8V \pm 0.15V$ | | $V_{CC} = 2.5V \pm 0.2V$ | | $V_{CC} = 3.3V \pm 0.3V$ | | $V_{CC} = 5V \pm 0.5V$ | | Unit |
|-----------|--------------|-------------|---------------------------|------|--------------------------|-----|--------------------------|-----|------------------------|-----|------|
| | | | Min | Max | Min | Max | Min | Max | Min | Max | |
| t_{pd} | Any | Y | 1.0 | 14.4 | 0.7 | 8.3 | 0.7 | 6.3 | 0.7 | 5.1 | ns |

$T_A = -40^\circ C$ to $+125^\circ C$, $C_L = 30$ or $50pF$ as noted (See Figure 1)

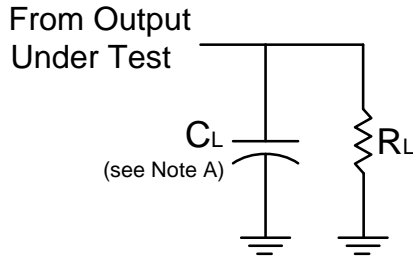
| Parameter | From (Input) | TO (OUTPUT) | $V_{CC} = 1.8V \pm 0.15V$ | | $V_{CC} = 2.5V \pm 0.2V$ | | $V_{CC} = 3.3V \pm 0.3V$ | | $V_{CC} = 5V \pm 0.5V$ | | Unit |
|-----------|--------------|-------------|---------------------------|------|--------------------------|------|--------------------------|-----|------------------------|-----|------|
| | | | Min | Max | Min | Max | Min | Max | Min | Max | |
| t_{pd} | Any | Y | 1.0 | 18.0 | 0.7 | 10.4 | 0.7 | 7.9 | 0.7 | 6.4 | ns |

Operating Characteristics

$T_A = +25^\circ C$

| Parameter | Test Conditions | $V_{CC} = 1.8V$ | $V_{CC} = 2.5V$ | $V_{CC} = 3.3V$ | $V_{CC} = 5V$ | Unit | |
|-----------|-------------------------------|-----------------|-----------------|-----------------|---------------|------|----|
| | | Typ. | Typ. | Typ. | Typ. | | |
| C_{pd} | Power dissipation capacitance | $f = 10$ MHz | 22 | 22 | 23 | 24 | pF |

Parameter Measurement Information



| V _{CC} | Inputs | | V _M | C _L | R _L |
|-----------------|-----------------|--------------------------------|--------------------|----------------|----------------|
| | V _I | t _r /t _f | | | |
| 1.8V±0.15V | V _{CC} | ≤2ns | V _{CC} /2 | 30pF | 1KΩ |
| 2.5V±0.2V | V _{CC} | ≤2ns | V _{CC} /2 | 30pF | 500Ω |
| 3.3V±0.3V | 3V | ≤2.5ns | 1.5V | 50pF | 500Ω |
| 5V±0.5V | V _{CC} | ≤2.5ns | V _{CC} /2 | 50pF | 500Ω |

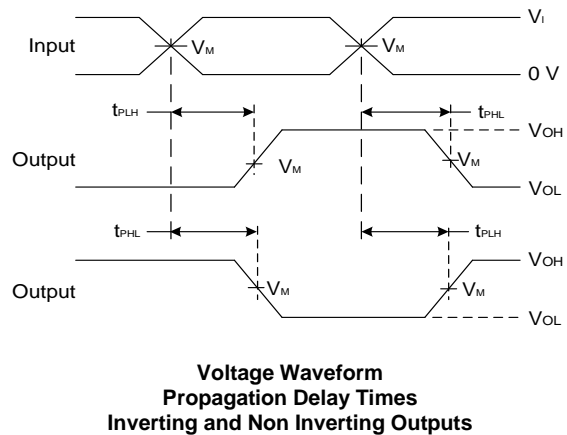
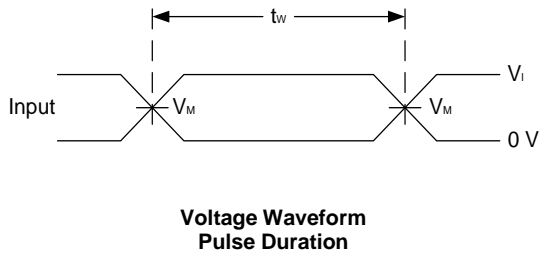
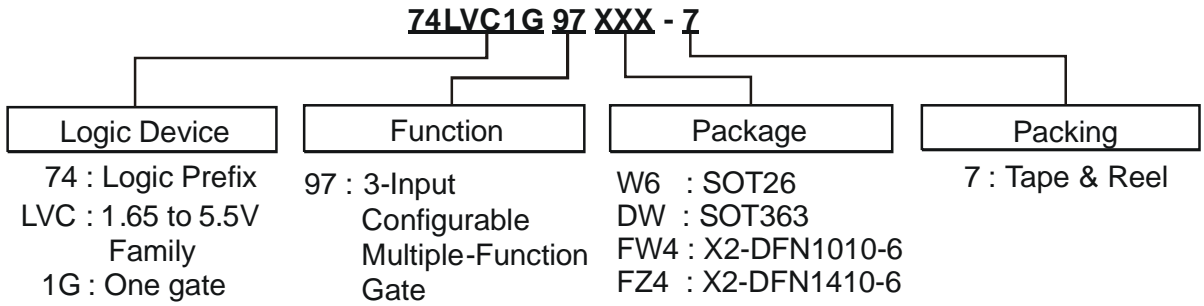


Figure 1 Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD}.

Ordering Information (Note 7)

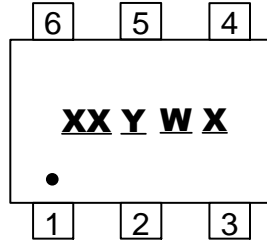


| Device | Package Code | Packaging | 7" Tape and Reel | |
|----------------|--------------|--------------|-------------------|--------------------|
| | | | Quantity | Part Number Suffix |
| 74LVC1G97W6-7 | W6 | SOT26 | 3,000/Tape & Reel | -7 |
| 74LVC1G97DW-7 | DW | SOT363 | 3,000/Tape & Reel | -7 |
| 74LVC1G97FW4-7 | FW4 | X2-DFN1010-6 | 5,000/Tape & Reel | -7 |
| 74LVC1G97FZ4-7 | FZ4 | X2-DFN1410-6 | 5,000/Tape & Reel | -7 |

Note: 7. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

(1) SOT26, SOT363

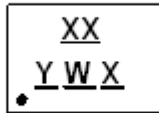


XX : Identification code
Y : Year 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week
X : A~Z : Internal Code

| Part Number | Package | Identification Code |
|-------------|---------|---------------------|
| 74LVC1G97W6 | SOT26 | TY |
| 74LVC1G97DW | SOT363 | TY |

(2) X2-DFN1010-6, X2-DFN1410-6

(Top View)



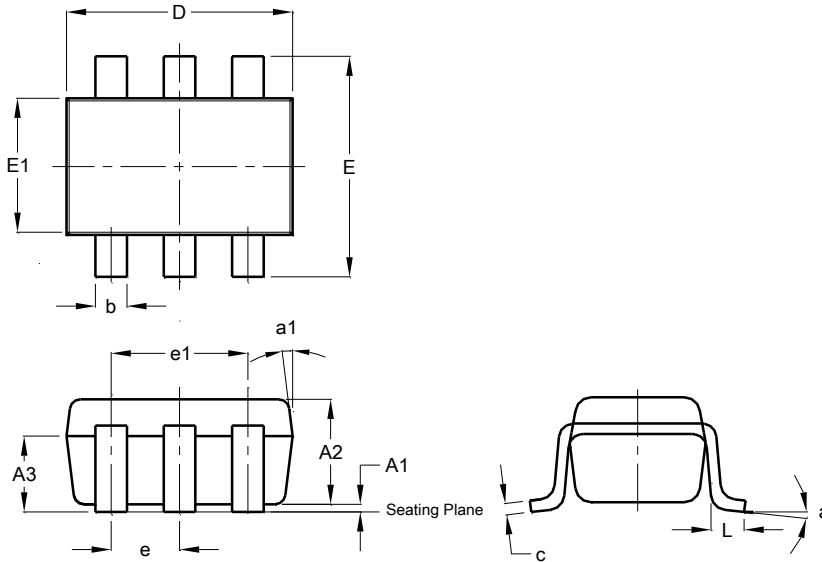
XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week
X : A~Z : Internal code

| Part Number | Package | Identification Code |
|--------------|--------------|---------------------|
| 74LVC1G97FW4 | X2-DFN1010-6 | TY |
| 74LVC1G97FZ4 | X2-DFN1410-6 | TY |

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26

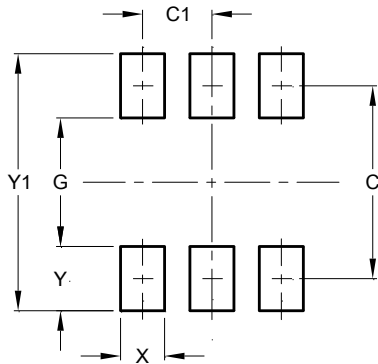


| SOT26 | | | |
|----------------------|-------|------|------|
| Dim | Min | Max | Typ |
| A1 | 0.013 | 0.10 | 0.05 |
| A2 | 1.00 | 1.30 | 1.10 |
| A3 | 0.70 | 0.80 | 0.75 |
| b | 0.35 | 0.50 | 0.38 |
| c | 0.10 | 0.20 | 0.15 |
| D | 2.90 | 3.10 | 3.00 |
| e | - | - | 0.95 |
| e1 | - | - | 1.90 |
| E | 2.70 | 3.00 | 2.80 |
| E1 | 1.50 | 1.70 | 1.60 |
| L | 0.35 | 0.55 | 0.40 |
| a | - | - | 8° |
| a1 | - | - | 7° |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26



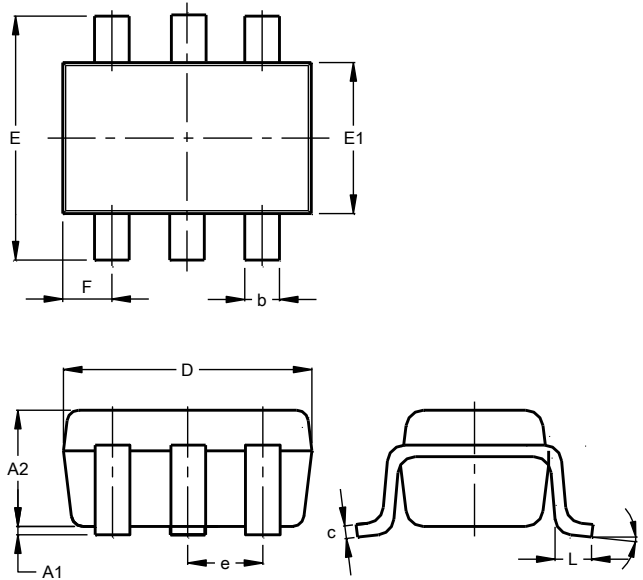
| Dimensions | Value (in mm) |
|------------|---------------|
| C | 2.40 |
| C1 | 0.95 |
| G | 1.60 |
| X | 0.55 |
| Y | 0.80 |
| Y1 | 3.20 |

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363

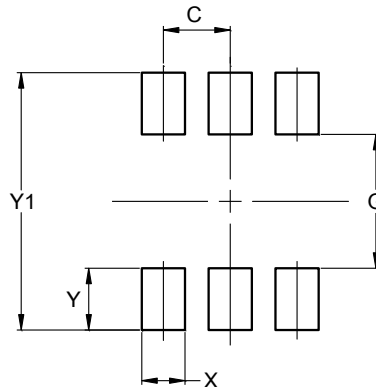


| SOT363 | | | |
|-----------------------------|-----------|------|-------|
| Dim | Min | Max | Typ |
| A1 | 0.00 | 0.10 | 0.05 |
| A2 | 0.90 | 1.00 | 0.95 |
| b | 0.10 | 0.30 | 0.25 |
| c | 0.10 | 0.22 | 0.11 |
| D | 1.80 | 2.20 | 2.15 |
| E | 2.00 | 2.20 | 2.10 |
| E1 | 1.15 | 1.35 | 1.30 |
| e | 0.650 BSC | | |
| F | 0.40 | 0.45 | 0.425 |
| L | 0.25 | 0.40 | 0.30 |
| a | 0° | 8° | -- |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363



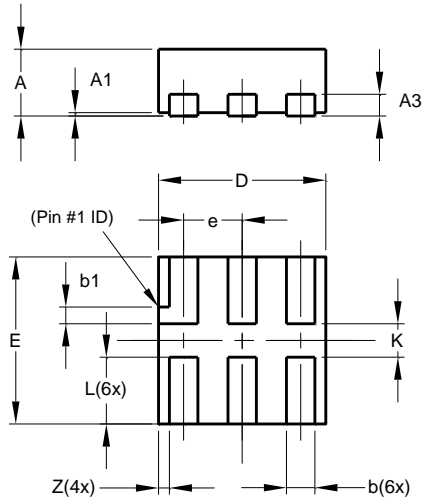
| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.650 |
| G | 1.300 |
| X | 0.420 |
| Y | 0.600 |
| Y1 | 2.500 |

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6

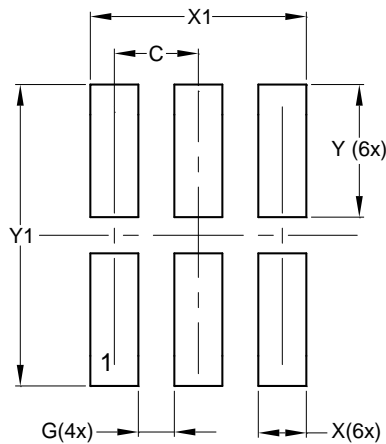


| X2-DFN1010-6 | | | |
|----------------------|------|------|-------|
| Dim | Min | Max | Typ |
| A | — | 0.40 | 0.39 |
| A1 | 0.00 | 0.05 | 0.02 |
| A3 | — | — | 0.13 |
| b | 0.14 | 0.20 | 0.17 |
| b1 | 0.05 | 0.15 | 0.10 |
| D | 0.95 | 1.05 | 1.00 |
| E | 0.95 | 1.05 | 1.00 |
| e | — | — | 0.35 |
| L | 0.35 | 0.45 | 0.40 |
| K | 0.15 | — | — |
| Z | — | — | 0.065 |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6



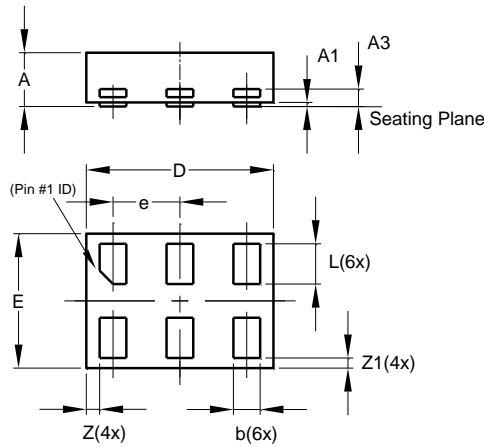
| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.350 |
| G | 0.150 |
| X | 0.200 |
| X1 | 0.900 |
| Y | 0.550 |
| Y1 | 1.250 |

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1410-6

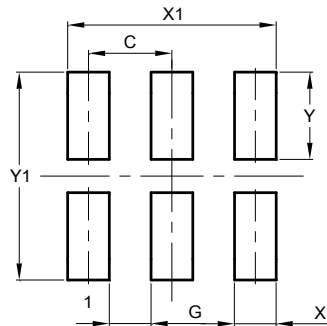


| X2-DFN1410-6 | | | |
|-----------------------------|-------|-------|-------|
| Dim | Min | Max | Typ |
| A | — | 0.40 | 0.39 |
| A1 | 0.00 | 0.05 | 0.02 |
| A3 | — | — | 0.13 |
| b | 0.15 | 0.25 | 0.20 |
| D | 1.35 | 1.45 | 1.40 |
| E | 0.95 | 1.05 | 1.00 |
| e | — | — | 0.50 |
| L | 0.25 | 0.35 | 0.30 |
| Z | — | — | 0.10 |
| Z1 | 0.045 | 0.105 | 0.075 |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1410-6



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.500 |
| G | 0.250 |
| X | 0.250 |
| X1 | 1.250 |
| Y | 0.525 |
| Y1 | 1.250 |

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These dimensions may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

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